

In the Specification

Please amend the paragraph on page 28 at lines 5-24 as follows:

C' A two-layer FPC substrate (film or sheet) 257 has copper-foil wiring patterns 261 sandwiched between resin layers 258 formed from heat-resisting resin, such as polyimide. The FPC substrate 257 is bonded to a metal block 251 formed from metallic material, by means of a thermosetting adhesive 365 (see Fig. 8). The number of layers of FPC substrates 257 may be increased, as necessary. Self-scan-type light-emitting device array chips 250 are mounted into a row and at predetermined locations on the surface of copper foil 262 laid on the surface of the FPC substrate bonded to the metal block 251. The array chips 250 are arranged by means of a die bonder and fixed by means of a conductive adhesive. Fig. 6 shows an example in which the array chips 250 are arranged in a staggered layout. However, the array chips 250 can be arranged in a straight line. Before the FPC substrate 257 is assembled into an optical write head, electrode pads 258A provided on the light-emitting array chips 250 having the light-emitting devices 252 mounted thereon are electrically connected, by means of wire bonding, to conductor pads 270 located at predetermined locations within an area 267 of the FPC substrate 257 from which a resin layer has been partially removed.